

REMARKS/ARGUMENTS

Favorable reconsideration of this application as presently amended and in light of the following remarks is respectfully requested

Claims 1, 4-6, 21-24 and 39-41 are presently active in this application; Claims 1, 6, 21, 23, 24 and 39 having been amended and new Claims 42-44 added by the present amendment, and Claims 2, 3, 7-20 and 25-38 having been withdrawn from consideration as directed to a non-elected invention.

In the outstanding Office Action Claims 1, 4-6, 21-24 and 39-41 were objected to as including informalities requiring correction and Claims 1, 4-6, 21-24 and 39-41 were rejected under 35 USC §103(a) as being unpatentable over Narazaki et al (6,285,058, hereinafter called "Narazaki") in view of Applicants' Admitted Prior Art ("APA").

In light of the outstanding ground for rejection, Claim 1 has been amended to clarify that the upper surfaces of the main electrodes are higher than --the highest portion of-- an upper surface of the gate wiring in the claimed semiconductor device recited in Claim 1. By virtue of this claimed structure, it possible to reduce shock applied to a first insulating film when a connecting plate is connected onto the upper surfaces of the main electrodes. The APA includes no such teaching.

On the other hand, as taught by Narazaki, an upper surface of a main electrode 14 is at the same level as the highest portion of an upper surface of a gate wiring 13. Therefore, shock is applied to a first insulating film 6 when a connecting plate is connected onto the upper surface of main electrode 14.

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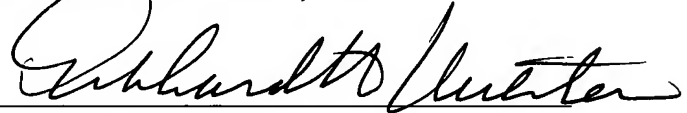
Accordingly, Narazaki fails to cure the deficiency of the APA and it is therefore respectfully submitted that amended Claim 1 and the claims dependent therefrom patentably define over the cited art and are in condition for allowance.

As the remaining independent Claims 6 and 24 have also been amended to recite explicitly that an upper surface of a main electrode is higher than the highest portion of an upper surface of the gate wiring, it is respectfully submitted that for the reasons above noted, Claims 6 and 24 as well as the claims dependent therefrom likewise patentably define over the cited art and likewise are in condition for allowance.

Consequently, in view of the present amendment and in light of the above discussion, no further issues are believed to be outstanding, and the present application is believed to be in condition for formal allowance. An early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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